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Brightening the Future

Financial Results of FY2023 First-Half

From April 1, 2023 to September 30, 2023

SHINKO ELECTRIC INDUSTRIES CO., LTD.



Financial Results Overview of FY2023 First-Half (consolidated)

| | |
|-------------------------------|----|
| Financial Results | 2 |
| Plastic Packages | 6 |
| Metal Packages | 8 |
| Net Sales by Product Category | 10 |

Forecast of FY2023 (consolidated)

| | |
|--|----|
| Revised Forecast of FY2023 (Announcement on October 20, 2023) | 11 |
| Net Sales/Profit/Cash Dividend | 13 |
| Capital Expenditure, Depreciation, Research and Development | 15 |

Financial Results Overview of FY2023 First-Half (consolidated)

Financial Results

(Billions of yen)

| | FY2022 1st-Half (Result) | FY2023 1st-Half (Result) | YoY | | vs. Previous Forecast | |
|---|--------------------------------|--------------------------------|--------|--------------------|-------------------------------------|--------|
| | | | Amount | Ratio of Change | Previous Forecast (4/27/2023) | Amount |
| Net Sales | 157.0 | 105.1 | -51.9 | -33% | 112.0 | -6.9 |
| Operating Profit (Ratio against Net Sales) | 51.0 (+32%) | 11.5 (+11%) | -39.5 | -77% | 8.0 | +3.5 |
| Ordinary Profit (Ratio against Net Sales) | 54.6 (+35%) | 14.1 (+13%) | -40.6 | -74% | 8.0 | +6.1 |
| Profit* (Ratio against Net Sales) | 37.9 (+24%) | 9.8 (+9%) | -28.1 | -74% | 6.0 | +3.8 |

* Profit attributable to owners of parent

| | | |
|--------------------|-----------|----------|
| Earnings per Share | 280.34yen | 72.39yen |
|--------------------|-----------|----------|

Financial Results Overview of FY2023 First-Half (consolidated)

Summary of Financial Statements

- In the semiconductor industry, while decline in demand has showed signs of bottoming out, market recovery delayed and a severe market environment continued due to a decline in PC and server markets as a negative rebound from the special demand for COVID-19, a drop in demand for smartphones caused by longer replacement cycles, and inventory adjustments in addition to continued global inflation and the impact of US-China conflict.
- Net Sales of flip-chip type packages decreased largely due to delayed recovery in demand for PCs and servers. Revenue from leadframes declined due to inventory adjustments, and revenue from ceramic electrostatic chucks for semiconductor manufacturing equipment decreased against the backdrop of semiconductor export restrictions and the market deterioration. Demand for IC assemblies for high-end smartphones dropped. So, overall sales conditions were affected by the market downdraft.
- Net sales down 33% year on year. All profits decreased due to the large impact of sales down.

Financial Results Overview of FY2023 First-Half (consolidated)

Net Sales and Ordinary Profit by Business Segment

(Billions of yen)

| | | FY2022 1st-Half (Result) | | FY2023 1st-Half (Result) | | Ratio of Change (YoY) | FY2022 | |
|--------------------|-------------------|--------------------------------|-----------------------------|--------------------------------|-----------------------------|-----------------------------|--------------|-----------------------------|
| | | | Represent % of Net Sales | | Represent % of Net Sales | | | Represent % of Net Sales |
| Net Sales *1 | Plastic Packages | 95.6 | [61%] | 65.4 | [62%] | -32% | 176.8 | [62%] |
| | Metal Packages | 55.8 | [35%] | 35.4 | [34%] | -37% | 99.3 | [35%] |
| | Others | 5.6 | [4%] | 4.3 | [4%] | -23% | 10.2 | [3%] |
| | Total | 157.0 | [100%] | 105.1 | [100%] | -33% | 286.4 | [100%] |
| Ordinary Profit *2 | Plastic Packages | 34.3 | (+36%) | 7.1 | (+11%) | -79% | 47.3 | (+27%) |
| | Metal Packages | 20.2 | (+36%) | 8.0 | (+23%) | -61% | 31.2 | (+31%) |
| | Others/Adjustment | 0.2 | | -1.0 | | | 0.2 | |
| | Total | 54.6 | (+35%) | 14.1 | (+13%) | -74% | 78.8 | (+28%) |

*1 Sales to external customers

*2 Before inter-segment transaction adjustment

Financial Results Overview of FY2023 First-Half (consolidated)

Financial Status, Capital Expenditure and Depreciation

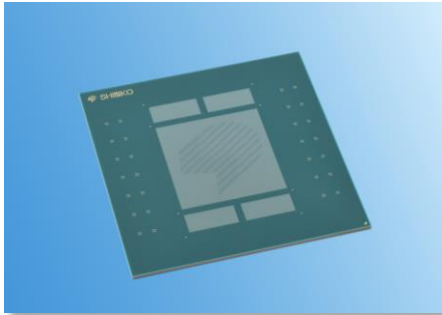
(Billions of yen)

| | FY2022 2nd-Quarter | FY2023 2nd-Quarter | FY2022 |
|-----------------------------------|-----------------------|-----------------------|--------|
| Total Assets | 376.1 | 389.6 | 386.9 |
| Net Assets | 237.5 | 258.5 | 251.0 |
| Equity Ratio | 63% | 66% | 65% |
| | FY2022 1st-Half | FY2023 1st-Half | FY2022 |
| Capital Expenditure* | 15.8 | 21.5 | 25.8 |
| Depreciation* | 16.1 | 12.8 | 34.5 |
| Research and Development | 1.8 | 1.7 | 3.6 |
| Exchange Rates (Yen/US dollar) | 132 | 139 | 134 |

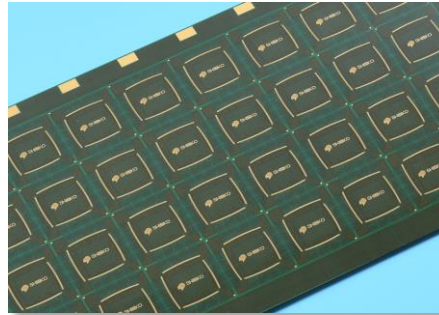
* Except intangible assets

Financial Results Overview of FY2023 First-Half (consolidated)

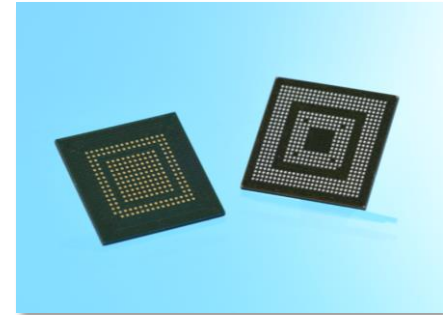
Plastic Packages



**Flip-Chip Type
Package**



**Plastic BGA
Substrates**



IC Assemblies

【Applications】

PCs, Servers, Smartphones, Consumer Products, etc.

Financial Results Overview of FY2023 First-Half (consolidated)

Plastic Packages

(Billions of yen)

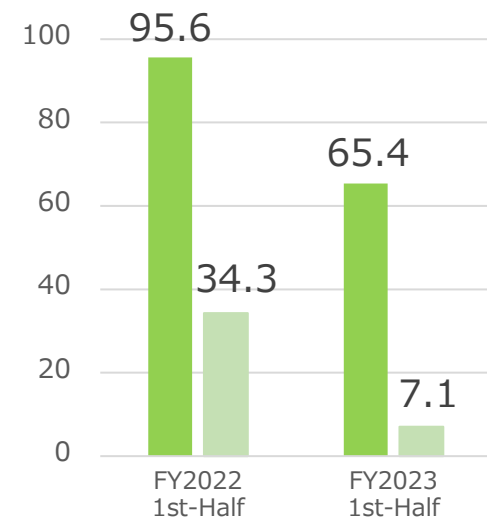
| | FY2022 1st-Half (Result) | FY2023 1st-Half (Result) | YoY | |
|-----------------|--------------------------------|--------------------------------|--------|--------------------|
| | | | Amount | Ratio of Change |
| Net Sales | 95.6 [61%]* ¹ | 65.4 [62%]* ¹ | - 30.2 | - 32% |
| Ordinary Profit | 34.3 (+36%)* ² | 7.1 (+11%)* ² | - 27.1 | - 79% |

*1 Represent % of Net Sales *2 Ratio against Net Sales

■ Net sales ■ Ordinary Profit

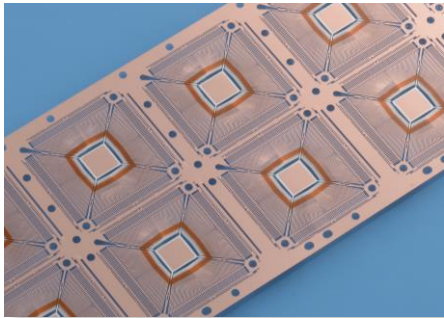
Net sales and ordinary profit both decreased year on year due to the decrease in sales of each product.

- Net sales of flip-chip type packages decreased largely due to delayed recovery in demand for PCs and servers as a negative rebound from the special demand for COVID-19, and other factors.
- Net sales of IC assemblies decreased due to a drop in demand for high-end smartphone because of the smartphone market downdraft.
- Net sales of plastic BGA substrates decreased due to inventory adjustments in advanced memory.

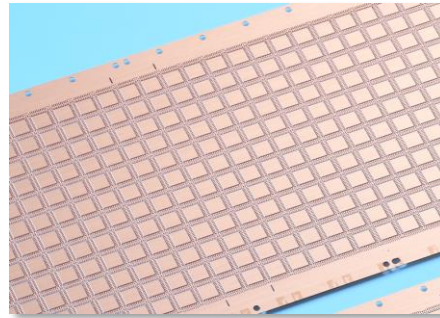


Financial Results Overview of FY2023 First-Half (consolidated)

Metal Packages



Stamped Leadframes



Etched Leadframes
(QFN-Type)



Ceramic Electrostatic
Chuck



Glass-to-Metal Seals



Heat Spreaders

【Applications】

Automobiles, Smartphones, Consumer Products, Semiconductor Manufacturing Equipment, Communications Equipment etc.

Financial Results Overview of FY2023 First-Half (consolidated)

Metal Packages

(Billions of yen)

| | FY2022 1st-Half (Result) | FY2023 1st-Half (Result) | YoY | |
|-----------------|--------------------------------|--------------------------------|--------|--------------------|
| | | | Amount | Ratio of Change |
| Net Sales | 55.8 [35%]* ¹ | 35.4 [34%]* ¹ | -20.4 | -37% |
| Ordinary Profit | 20.2 (+36%)* ² | 8.0 (+23%)* ² | -12.2 | -61% |

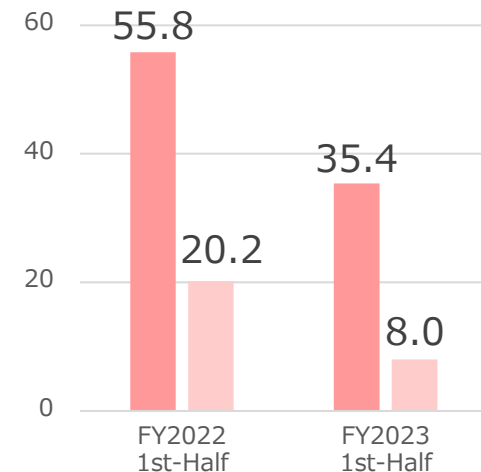
*1 Represent % of Net Sales

*2 Ratio against Net Sales

Net sales and ordinary profit both decreased year on year due to the decrease in sales of each product.

- Net sales of leadframes decreased largely, due to big impact of inventory adjustments, etc. because of the downdraft in the semiconductor market.
- Net sales of ceramic electrostatic chucks decreased largely reflected the backdrop of impact of semiconductor export restrictions because of US-China conflict and the memory market deterioration, etc.
- Net sales of heat spreaders for CPUs decreased due to a decline in demand for PCs, and other factors.
- Revenue of glass-to-metal-seals decreased due to the sluggish sales for optical devices.

■ Net sales ■ Ordinary Profit



Financial Results Overview of FY2023 First-Half (consolidated)

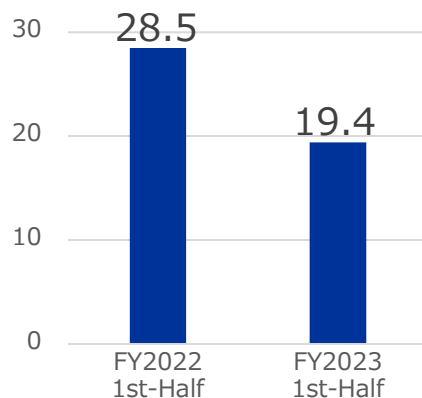
Net Sales by Product Category

(Billions of yen)

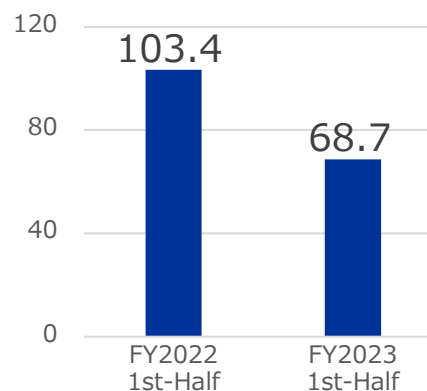
| | FY2022 1st-Half (Result) | FY2023 1st-Half (Result) | YoY | | FY2022 (Result) |
|---------------------|--------------------------------|--------------------------------|--------|--------------------|--------------------|
| | | | Amount | Ratio of Change | |
| IC Leadframes | 28.5 [18%]* | 19.4 [19%]* | -9.1 | -32% | 49.7[17%]* |
| IC Packages | 103.4 [66%]* | 68.7 [65%]* | -34.7 | -34% | 187.9[66%]* |
| Hermetic Seal Parts | 25.1 [16%]* | 17.0 [16%]* | -8.1 | -32% | 48.7[17%]* |

* Represent % of Net Sales

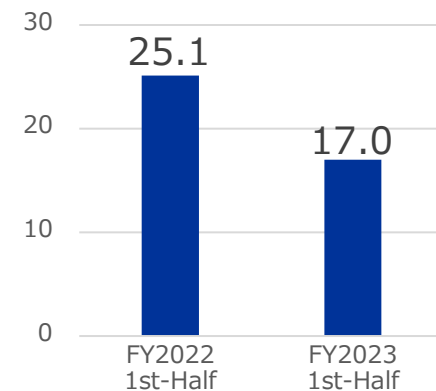
Net Sales of
IC Leadframes



Net Sales of
IC Packages



Net Sales of
Hermetic Seal Parts



Forecast of FY2023 (consolidated)

Revised Forecast of FY2023 (Announcement on October 20, 2023)

(Billions of yen)

| | FY2023 1st-Half | | | | FY2023 | | | |
|--------------------|----------------------------------|----------------------|-----------------------|-----------------|----------------------------------|----------------------------------|-----------------------|-----------------|
| | Previous Forecast (4/27/2023) | 1st Half (Result) | vs. Previous Forecast | | Previous Forecast (4/27/2023) | Current Forecast (10/20/2023) | vs. Previous Forecast | |
| | | | Amount | Ratio of Change | | | Amount | Ratio of Change |
| Net Sales | 112.0 | 105.1 | -6.9 | -6% | 261.0 | 230.0 | -31.0 | -12% |
| Operating Profit | 8.0 | 11.5 | +3.5 | +43% | 35.0 | 35.0 | 0.0 | 0% |
| Ordinary Profit | 8.0 | 14.1 | +6.1 | +76% | 35.0 | 35.0 | 0.0 | 0% |
| Profit* | 6.0 | 9.8 | +3.8 | +63% | 24.0 | 24.0 | 0.0 | 0% |
| Earnings per Share | 44.41yen | 72.39yen | - | - | 177.63yen | 177.63yen | - | - |

* Profit attributable to owners of parent

Forecast of FY2023 (consolidated)

Revised Forecast of FY2023 First-Half and FY2023 (Announcement on October 20, 2023)

- Reasons for the Revision of FY2023 First-Half
 - Net sales fell short of the initial forecast due to remained sluggish order of flip-chip type packages for PCs and servers and ceramic electrostatic chucks for semiconductor manufacturing equipment. On the other hand, profits exceeded the initial forecast due to large yen depreciation against our assumption and other factors.
- Reasons for the Revision of FY2023
 - Although orders principally in flip-chip type packages are expected to show an increasing trend in the future, full-scale recovery of the semiconductor market is expected to take longer than our forecast at the beginning of this fiscal year. Under these conditions, while net sales of each product fall short of the expectations, we revised expected exchange rate from 120 yen per dollar to 135 yen per dollar from the third-quarter considering exchange rate trends. Based on these factors and others, we revised the forecast of FY2023.

Forecast of FY2023 (consolidated)

Net Sales/Profit/Cash Dividend

(Billions of yen)

| | FY2022 (Result) | | | FY2023 (1 st HF:Result·2 nd HF:Forecast) | | | YoY(Upper : Amount/Lower : Ratio of Change) | | |
|--|----------------------|----------------------|----------------|---|----------------------|----------------|---|----------------------|-----------------|
| | 1 st Half | 2 nd Half | FY 2022 | 1 st Half | 2 nd Half | FY 2023 | 1 st Half | 2 nd Half | Full Year |
| Net Sales | 157.0 | 129.4 | 286.4 | 105.1 | 124.9 | 230.0 | -51.9 (-33%) | -4.5 (-3%) | -56.4 (-20%) |
| Operating Profit (Ratio against Net Sales) | 51.0 (+32%) | 25.8 (+20%) | 76.7 (+27%) | 11.5 (+11%) | 23.5 (+19%) | 35.0 (+15%) | -39.5 (-77%) | -2.2 (-9%) | -41.7 (-54%) |
| Ordinary Profit (Ratio against Net Sales) | 54.6 (+35%) | 24.1 (+19%) | 78.8 (+28%) | 14.1 (+13%) | 20.9 (+17%) | 35.0 (+15%) | -40.6 (-74%) | -3.2 (-13%) | -43.8 (-56%) |
| Profit *1 (Ratio against Net Sales) | 37.9 (+24%) | 16.6 (+13%) | 54.5 (+19%) | 9.8 (+9%) | 14.2 (+11%) | 24.0 (+10%) | -28.1 (-74%) | -2.4 (-14%) | -30.5 (-56%) |
| Exchange Rates (Yen/US dollar) | 134 | | | 139 | 135 | | | | |

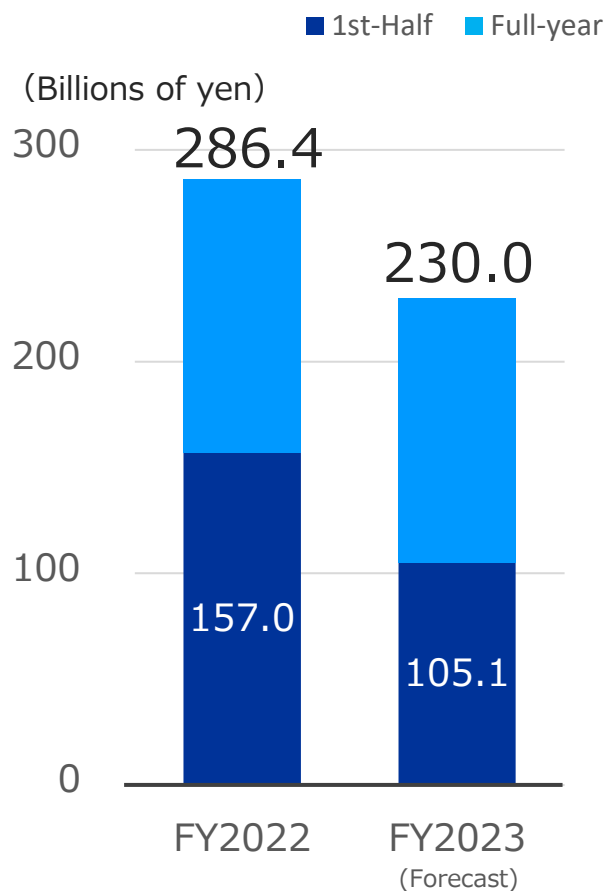
* Profit attributable to owners of parent

(Yen)

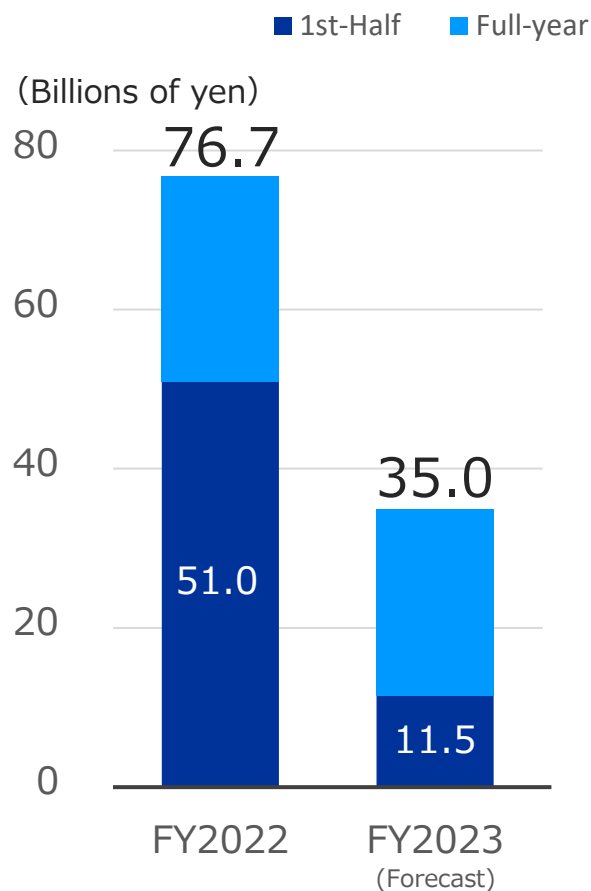
| | | | | | | |
|--|-------------------|--------------------|------------------|-------------------|--------------------|------------------|
| Cash Dividend per Share (Payout Ratio) | 25.0 [Interim] | 25.0 [Year-end] | 50.0 (+12.4%) | 25.0 [Interim] | 25.0 [Year-end] | 50.0 (+28.1%) |
|--|-------------------|--------------------|------------------|-------------------|--------------------|------------------|

Forecast of FY2023 (consolidated)

Net Sales

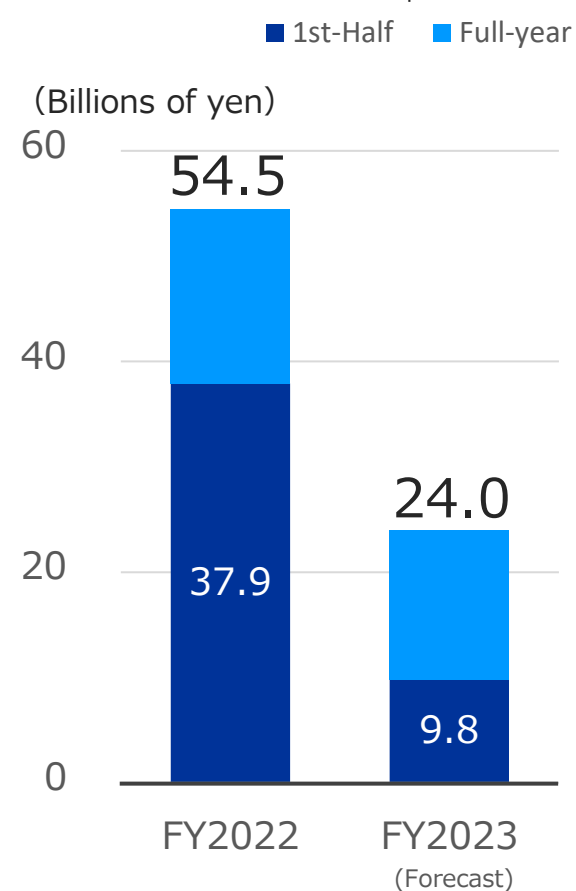


Operating Profit



Profit*

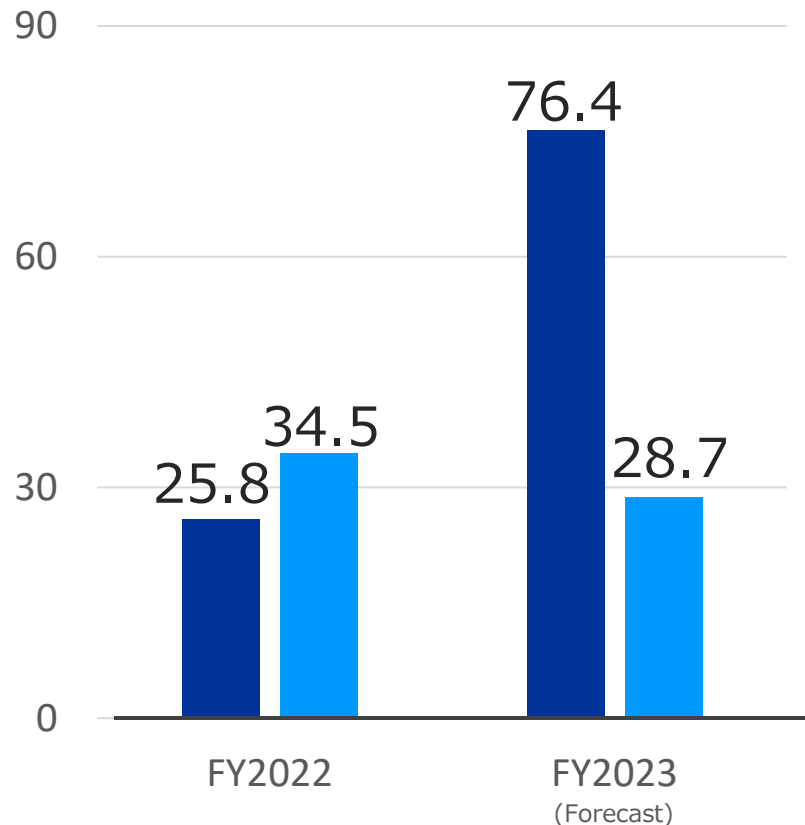
* Profit attributable to owners of parent



Forecast of FY2023 (consolidated)

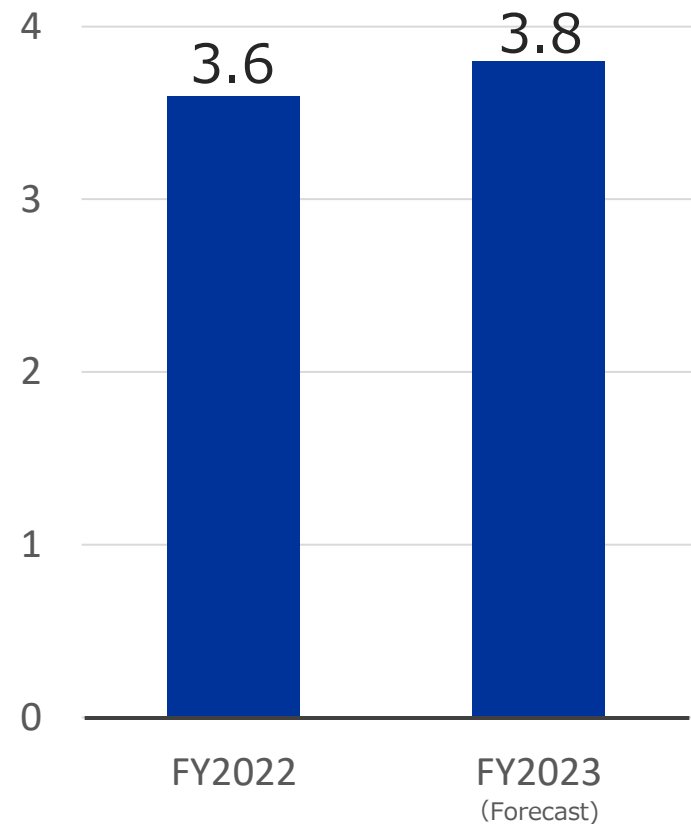
Capital Expenditure / Depreciation

(Billions of yen) ■ Capital Expenditure ■ Depreciation



Research and Development

(Billions of yen)



Notes to projected financial results:

The above projections were prepared based on estimates using information currently available. Actual results may differ from the projections. Also, many numerical values are shown in units of a billion yen as a general outline of business performance in this material. Because original values, which are managed in units of a million yen, are round off, the totals, difference, etc. shown in these materials may appear inaccurate. For assumptions and the other information regarding the projections, please refer to “the Financial Results” on IR library of our corporate website.